

Test & Burn-In Socket, GU78 molded frame series

Size 78x116.7mm / 3.07x4.59"

● Acceptable device size

Max. 48mm/1.89"
Max. 38mm/1.50"

In the case of larger size, consult factory.
Any device on 0.30mm pitch or larger



How to order

GU78-BGA □ □ □ □ □ □ □ □

P/N will be informed after fixing specifications.

example)
Probe pin socket

Features:

- High reliability
- Cost competitive
- Short delivery time
- Temperature -40°C to +150°C (typical)

In case BGA Device

352pin

This is an example. GRC Series socket can be used for other IC device and size.

device

(105°)

4-φ3.2
4-φ6 depth 5.6

(116.7)

23.55

(78)

68

55

36

35.2

1.27x25=31.75

1.27

56.6

32.6

4-φ3.2 (For M3 Screw)

352-φ0.6 (Au Pad)

φ2.05 (For Guide pin)

φ3.05 (For Guide pin)

PCB Pattern (Top View)

mm

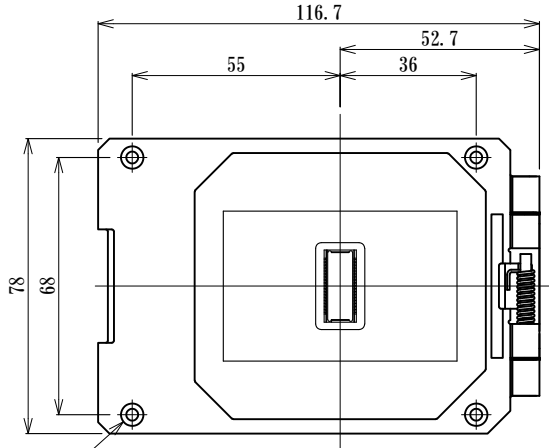
How to order

GU78-DIP□□□□□□□□

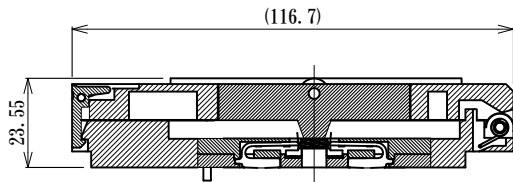
P/N will be informed after fixing specifications.

example)

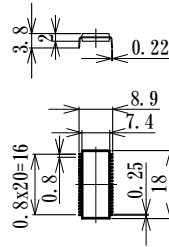
Stamping pin socket



4- ϕ 3.2
4- ϕ 6 depth 5.6

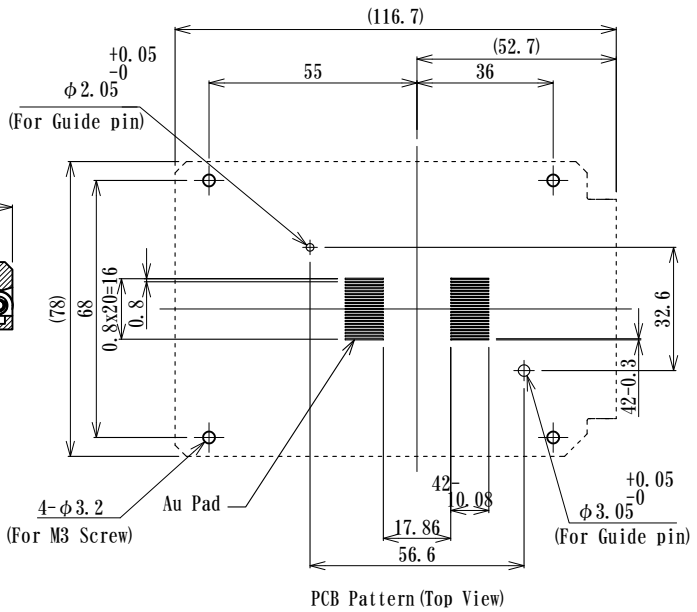
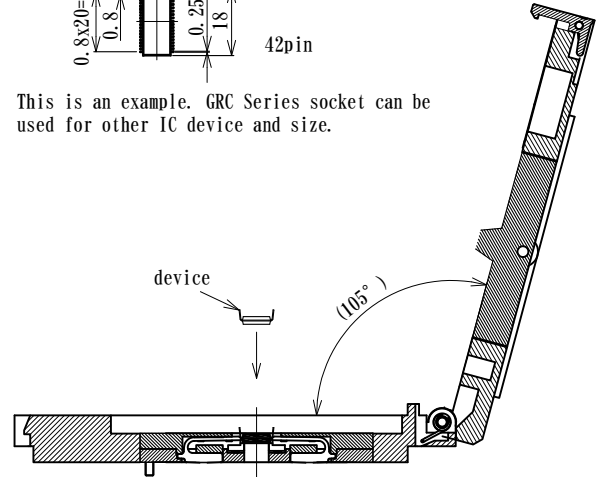


In case DIP Device



42pin

This is an example. GRC Series socket can be used for other IC device and size.



- Features:
- High reliability
 - Cost competitive
 - Short delivery time
 - Temperature
-40°C to +150°C
(typical)